Product / Package Information

Package	LQFP_EP
Lead Count	64
Body Size	10 X 10 X 1.4 (5.0 EP)
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.60 E-01	86.91	869100	28.37	283709
Thermosets	Epoxy and Phenol resin	Proprietary	2.35 E-02	12.78	127800	4.17	41719
Other inorganic materials	Carbon black	1333-86-4	5.69 E-04	0.31	3100	0.10	1012
Subtotal			1.84 E-01	100	1000000	32.64	326440

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.43 E-01	97.5	975000	61.06	610643
Copper & its alloys	Iron	7439-89-6	8.28 E-03	2.35	23500	1.47	14718
Copper & its alloys	Zinc	7440-66-6	4.23 E-04	0.12	1200	0.08	752
Copper & its alloys	Phosphorus	7723-14-0	1.06 E-04	0.03	300	0.02	188
Subtotal			3.52 E-01	100.00	1000000	62.63	626301

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.31 E-03	100	1000000	0.23	2326

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.35 E-03	100	1000000	0.42	4184

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.15 E-03	99	990000	0.38	3830
Precious Metals	Palladium	7440-05-3	2.18 E-05	1	10000	0.004	39
Subtotal			2.18 E-03	100	1000000	0.39	3869

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.92 E-02	100	1000000	3.41	34107

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.03 E-03	66.34	663400	0.18	1840
Thermoset	Epoxy resin	Proprietary	8.75 E-05	5.61	56100	0.02	156
Other organic materials	Aliphatic acid anhydride	Proprietary	8.75 E-05	5.61	56100	0.02	156
Other organic materials	2,6 diglycidyl phenyl allyl ether oligome	Proprietary	8.75 E-05	5.61	56100	0.02	156
Other organic materials	Epoxy derivative	Proprietary	8.75 E-05	5.61	56100	0.02	156
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	8.75 E-05	5.61	56100	0.02	156
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	8.75 E-05	5.61	56100	0.02	156
Subtotal			1.56 E-03	100.00	1000000	0.28	2774

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.62 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

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